



Building Information Modeling (BIM): Current Status, Applications and Trends

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Message from the Guest Editor

The digitization of the AEC sector has gone from being necessary to being essential. Advances in electronics, in hardware and software, as well as in wireless networks, allow a large amount of graphic and non-graphic information to be transferred at high speed. Design has taken off from flat (2D) to parametric design. Interoperability between multidisciplinary teams in real time is today easily assumable. Digital and remote control and monitoring of works, installations and infrastructures, with all kinds of devices and sensors, is today an efficient and sustainable alternative.

- AEC
- BIM
- digitalization
- 5G
- metaverse
- digital twins





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Message from the Editor-in-Chief

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